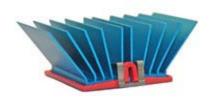
BGA Heat Sink - High Performance maxiFLOW/superGRIP





ATS Part#: ATS-X50170G-C1-R0

Description: 17.00 x 17.00 x 12.50 mm BGA Heat Sink - High

Performance maxiFLOW/superGRIP

Heat Sink Type: maxiFLOW
Heat Sink Attachment: superGRIP

Equivalent Part Number: N/A

*Image above is for illustration purpose only.

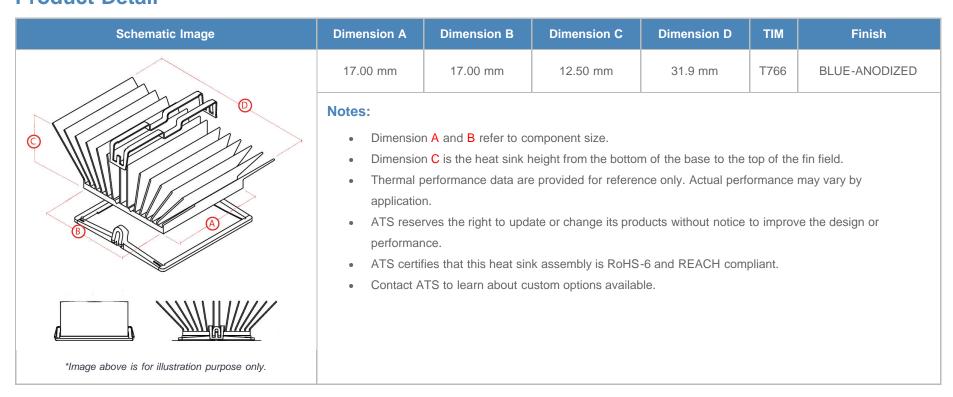
Features & Benefits

- Designed for 17x 17 mm components
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	11.1 °C/W	9.1 °C/W	7.9 °C/W	7.1 °C/W	6.5 °C/W	6 °C/W	5.7 °C/W
	Ducted Flow	9	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail







Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Advanced Thermal Solutions:

ATS-X50170G-C1-R0